

Dual N-Channel 75-V (D-S) MOSFET

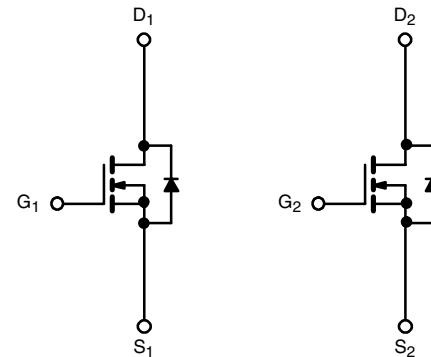
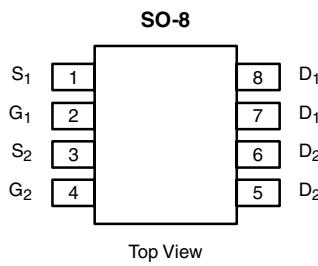
PRODUCT SUMMARY		
V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A)
75	0.048 at $V_{GS} = 10$ V	4.8
	0.062 at $V_{GS} = 4.5$ V	4.2

FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFETs
- 175 °C Maximum Junction Temperature
- High-Efficiency PWM Optimized
- Compliant to RoHS Directive 2002/95/EC



RoHS
COMPLIANT
HALOGEN
FREE
Available



Ordering Information: Si4992EY-T1-E3 (Lead (Pb)-free)
Si4992EY-T1-GE3 (Lead (Pb)-free and Halogen-free)

N-Channel MOSFET

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ABSOLUTE MAXIMUM RATINGS $T_A = 25$ °C, unless otherwise noted

Parameter	Symbol	10 s	Steady State	Unit
Drain-Source Voltage	V_{DS}	75	± 20	V
Gate-Source Voltage	V_{GS}			
Continuous Drain Current ($T_J = 175$ °C) ^a	I_D	4.8	3.6	A
		3.7	2.8	
Continuous Source Current ^a	I_S	2	1.1	
Pulsed Drain Current	I_{DM}	20		
Avalanche Current	I_{AS}	8		mJ
Single Avalanche Energy (Duty Cycle ≤ 1 %)	E_{AS}	3.2		
Maximum Power Dissipation ^a	P_D	2.4	1.4	W
		1.4	0.8	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to 175		°C

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^a	$t \leq 10$ s	R_{thJA}	50	62.5
	Steady State		85	110
Maximum Junction-to-Foot (Drain)	R_{thJF}	31	37	°C/W

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

SPECIFICATIONS $T_J = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}$, $I_D = 250 \mu\text{A}$	1		3	V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}$, $V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 75 \text{ V}$, $V_{GS} = 0 \text{ V}$		1		μA
		$V_{DS} = 75 \text{ V}$, $V_{GS} = 0 \text{ V}$, $T_J = 85^\circ\text{C}$		20		
On-State Drain Current ^a	$I_{D(\text{on})}$	$V_{DS} \geq 5 \text{ V}$, $V_{GS} = 10 \text{ V}$	20			A
Drain-Source On-State Resistance ^a	$R_{DS(\text{on})}$	$V_{GS} = 10 \text{ V}$, $I_D = 4.8 \text{ A}$		0.039	0.048	Ω
		$V_{GS} = 4.5 \text{ V}$, $I_D = 4.2 \text{ A}$		0.050	0.062	
Forward Transconductance ^a	g_{fs}	$V_{DS} = 15 \text{ V}$, $I_D = 4.8 \text{ A}$		16		S
Diode Forward Voltage ^a	V_{SD}	$I_S = 2.4 \text{ A}$, $V_{GS} = 0 \text{ V}$		0.8	1.2	V
Dynamic^b						
Total Gate Charge	Q_g	$V_{DS} = 38 \text{ V}$, $V_{GS} = 10 \text{ V}$, $I_D = 4.8 \text{ A}$		14	21	nC
Gate-Source Charge	Q_{gs}			2.4		
Gate-Drain Charge	Q_{gd}			3.5		
Gate Resistance	R_g	$f = 1 \text{ MHz}$		3.6		Ω
Turn-On Delay Time	$t_{d(\text{on})}$	$V_{DD} = 38 \text{ V}$, $R_L = 38 \Omega$ $I_D \geq 1 \text{ A}$, $V_{GEN} = 10 \text{ V}$, $R_g = 6 \Omega$		7	15	ns
Rise Time	t_r			10	15	
Turn-Off Delay Time	$t_{d(\text{off})}$			22	35	
Fall Time	t_f			10	15	
Source-Drain Reverse Recovery Time	t_{rr}	$I_F = 2.4 \text{ A}$, $di/dt = 100 \text{ A}/\mu\text{s}$		25	50	

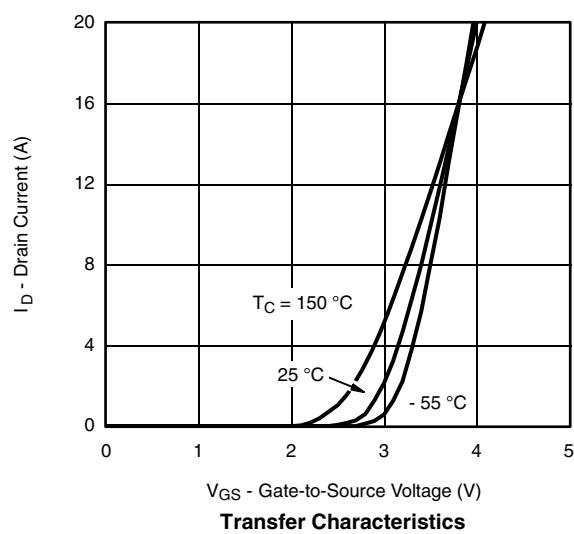
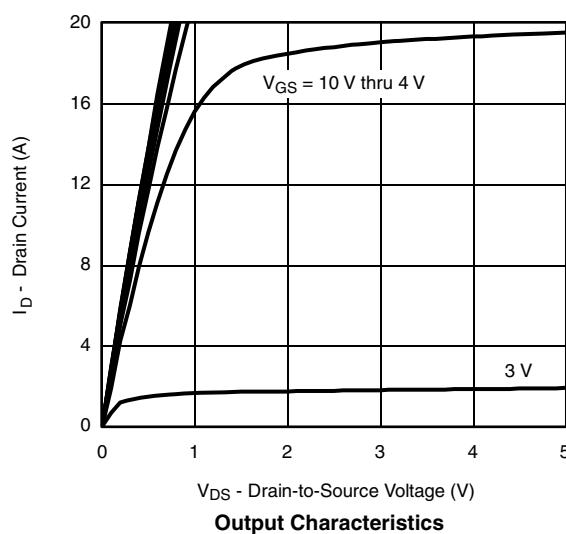
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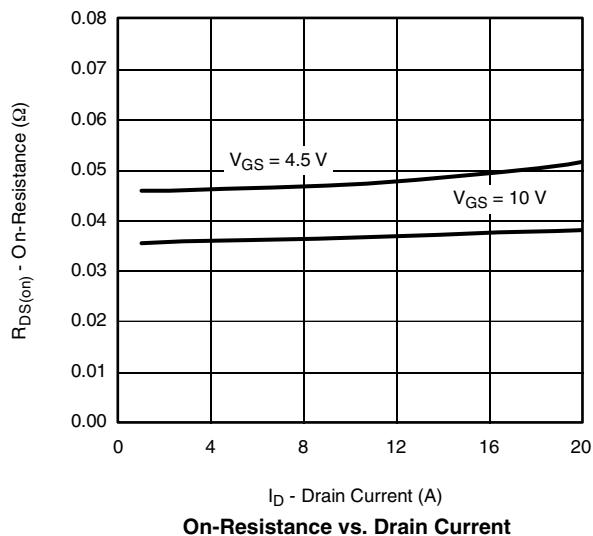
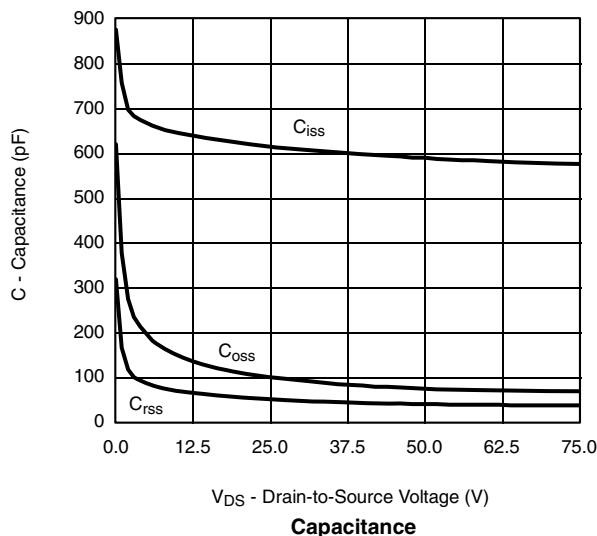
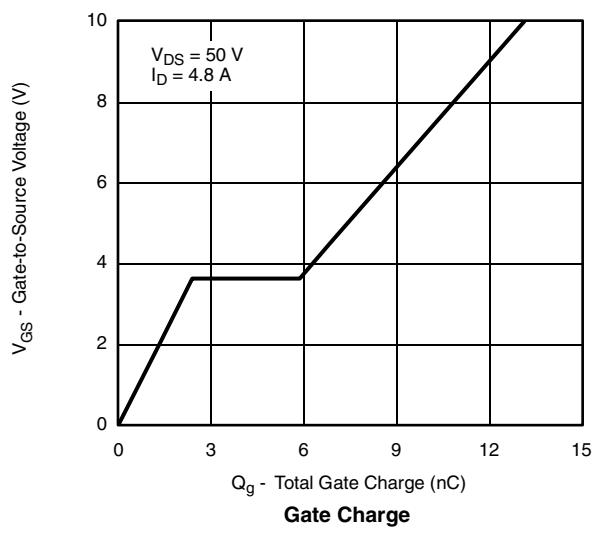
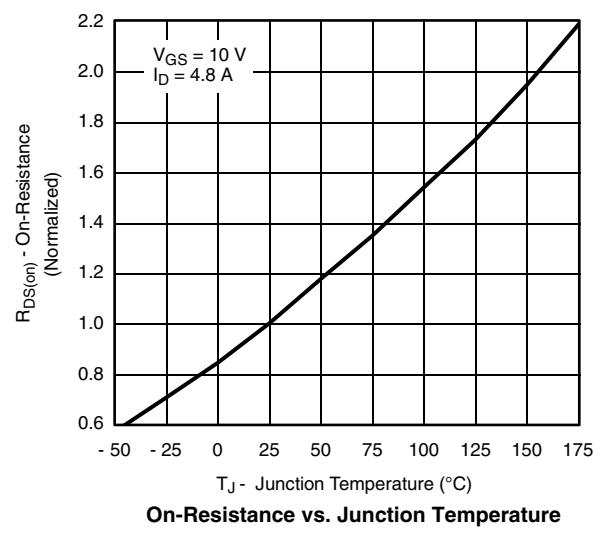
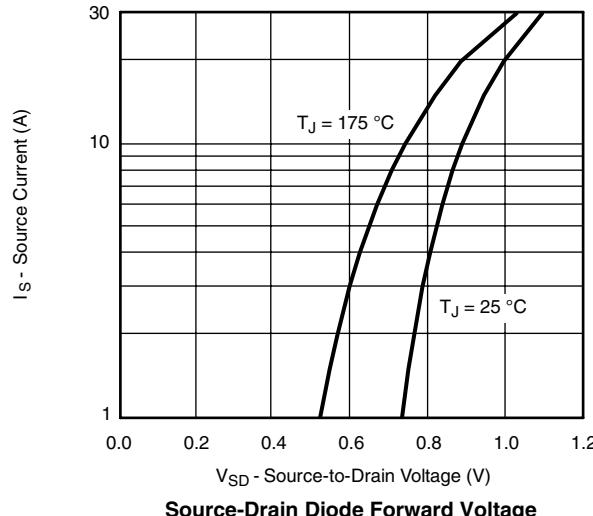
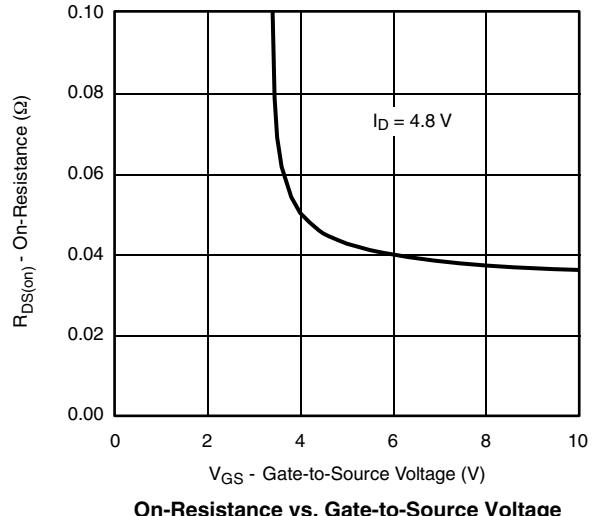
a. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2 \%$.

b. Guaranteed by design, not subject to production testing.

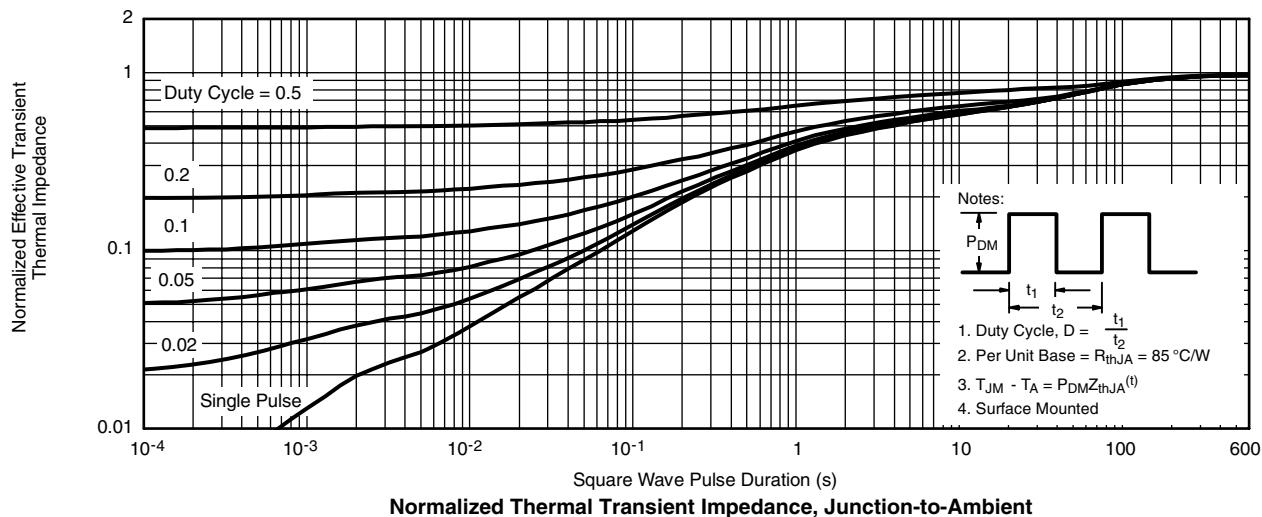
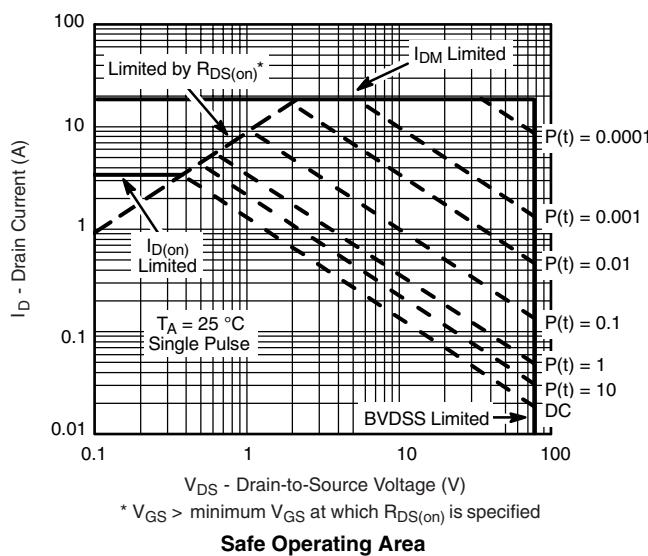
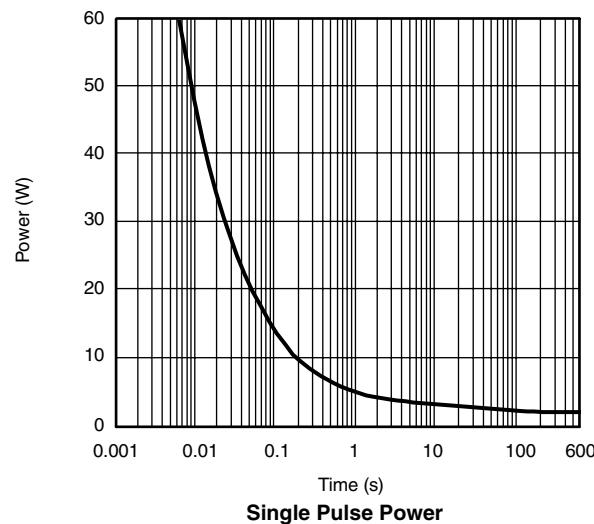
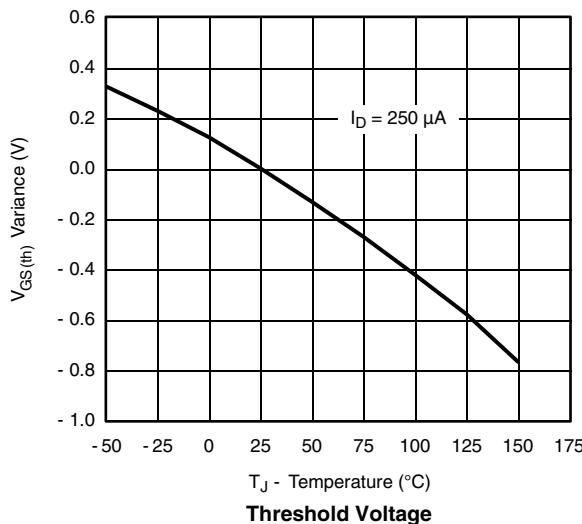
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

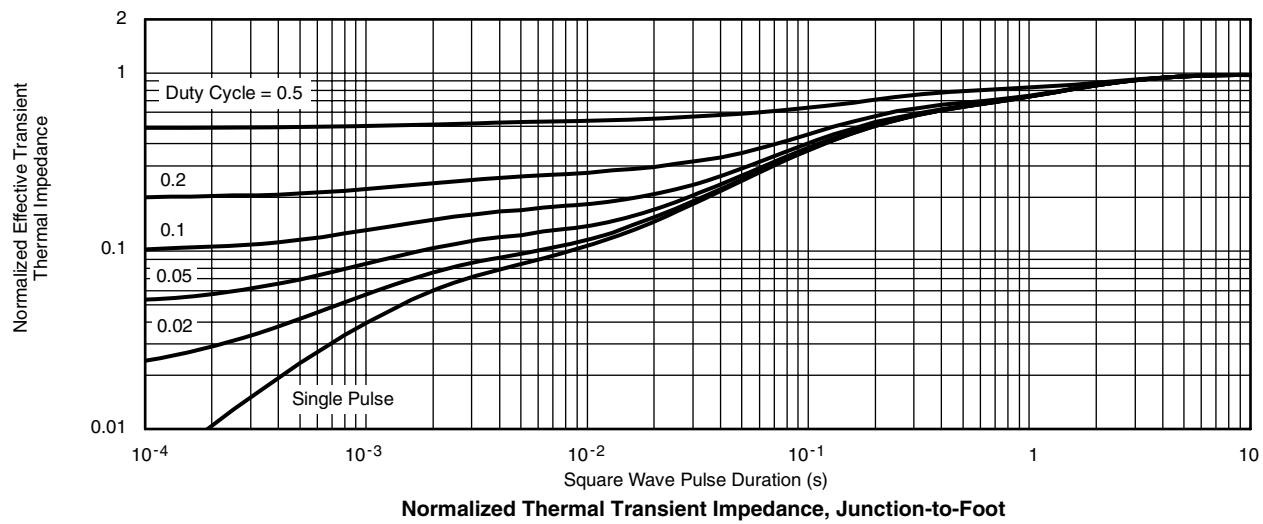
TYPICAL CHARACTERISTICS 25°C , unless otherwise noted



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On-Resistance vs. Drain Current

Capacitance

Gate Charge

On-Resistance vs. Junction Temperature

Source-Drain Diode Forward Voltage

On-Resistance vs. Gate-to-Source Voltage

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



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